



30V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

| BVDSS | Rds(on) Max | I _D Max T _A = +25°C |
|-------|--------------------------------|--|
| 00)/ | 10mΩ @ V _{GS} = -10V | -11A |
| -30V | 18mΩ @ V _{GS} = -4.5V | -8.3A |

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- Power management functions
- DC-DC converters

Features and Benefits

- Low Rds(ON) Ensures On-State Losses Are Minimized
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- Occupies just 33% of The Board Area Occupied by SO-8 Enabling Smaller End Product
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at

https://www.diodes.com/products/automotive/automotive-products/.

 This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.

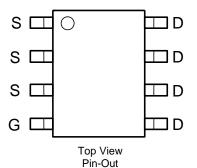
https://www.diodes.com/quality/product-definitions/

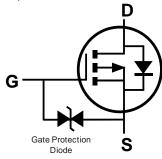
Mechanical Data

- Package: SO-8
- Package Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram Below
- Terminals: Finish Matte Tin Annealed over Copper Lead Frame.
 Solderable per MIL-STD-202, Method 208 (2)
- Weight: 0.074 grams (Approximate)









Equivalent Circuit

Top View

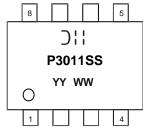
Ordering Information (Note 4)

| Part Number | Packago | Packing | | |
|---------------|---------|---------|-------------|--|
| | Package | Qty. | Carrier | |
| DMP3011SSS-13 | SO-8 | 2,500 | Tape & Reel | |

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



);; = Manufacturer's Marking
P3011SS = Product Type Marking Code
YYWW = Date Code Marking
YY or YY = Year (ex: 23 = 2023)
WW or <u>WW</u> = Week (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | | | Symbol | Value | Unit |
|---|-----------------|--|------------------|-------------|------|
| Drain-Source Voltage | | | VDSS | -30 | V |
| Gate-Source Voltage | | | V _{GSS} | ±25 | V |
| Continuous Drain Current (Note 6) V _{GS} = -10V | Steady State | T _A = +25°C T _A = +70°C | l _D | -11 -8.8 | А |
| Continuous Drain Current (Note 7) V _{GS} = -10V | Steady State | Tc = +25°C Tc = +70°C | l _D | -32 -26 | A |
| Maximum Continuous Body Diode Forward Current (Note 8) | | | Is | -2.4 | Α |
| Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%) | | | I _{DM} | -90 | Α |
| Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%) | | | I _{SM} | -90 | Α |
| Avalanche Current (Note 8) L = 1mH | | | las | -14 | Α |
| Avalanche Energy (Note 8) L = 1mH | | | Eas | 102 | mJ |

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

| Characteristic | | Symbol | Value | Unit |
|--|------------------------|-------------------|-------------|------|
| Total Power Dissipation (Note 5) | T _A = +25°C | PD | 1.4 | W |
| Thermal Resistance, Junction to Ambient (Note 5) | Steady State | RθJA | 90 | °C/W |
| Total Power Dissipation (Note 6) | T _A = +25°C | P _D | 1.8 | W |
| Thermal Resistance, Junction to Ambient (Note 6) Steady State | | RθJA | 68 | °C/W |
| Thermal Resistance, Junction to Case (Note 7) | | R ₀ JC | 8.2 | °C/W |
| Operating and Storage Temperature Range | | TJ, TSTG | -55 to +150 | °C |

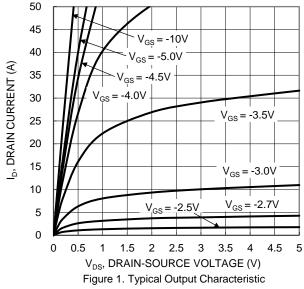
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
|--|---------------------|------|------|------|------|--|--|
| OFF CHARACTERISTICS (Note 9) | | | | | | | |
| Drain-Source Breakdown Voltage | BVpss | -30 | _ | _ | V | Vgs = 0V, Ip = -250µA | |
| Zero Gate Voltage Drain Current | I _{DSS} | _ | _ | -1 | μA | $V_{DS} = -24V, V_{GS} = 0V$ | |
| Gate-Source Leakage | I _{GSS} | _ | _ | ±10 | μA | $V_{GS} = \pm 25V, V_{DS} = 0V$ | |
| ON CHARACTERISTICS (Note 9) | | | | l | - | , 55 | |
| Gate Threshold Voltage | V _{GS(TH)} | -1.0 | _ | -3.0 | V | $V_{DS} = V_{GS}, I_{D} = -250 \mu A$ | |
| Chatia Duain Course On Bonistanes | | _ | 8 | 10 | mΩ | V _G S = -10V, I _D = -11.5A | |
| Static Drain-Source On-Resistance | RDS(ON) | _ | 13 | 18 | | V _G S = -4.5V, I _D = -8.5A | |
| Diode Forward Voltage | VsD | _ | -0.7 | -1.2 | V | V _G S = 0V, I _S = -1A | |
| DYNAMIC CHARACTERISTICS (Note 10) | | | | | | | |
| Input Capacitance | Ciss | _ | 2380 | | pF | 1 | |
| Output Capacitance | Coss | _ | 341 | _ | pF | V _{DS} = -15V, V _{GS} = 0V, | |
| Reverse Transfer Capacitance | Crss | _ | 296 | _ | pF | f = 1.0MHz | |
| Gate Resistance | Rg | _ | 3 | _ | Ω | $V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1.0MHz$ | |
| Total Gate Charge (VGS = -4.5V) | Qg | _ | 25 | _ | nC | | |
| Total Gate Charge (V _{GS} = -10V) | Qg | _ | 46 | _ | nC | 15)/ 14.54 | |
| Gate-Source Charge | Qgs | _ | 6.8 | _ | nC | $-V_{DS} = -15V, I_{D} = -11.5A$ | |
| Gate-Drain Charge | Qgd | _ | 13 | _ | nC | | |
| Turn-On Delay Time | t _{D(ON)} | _ | 6 | _ | ns | | |
| Turn-On Rise Time | t _R | _ | 22 | _ | ns | $V_{DD} = -15V$, $V_{GS} = -10V$, | |
| Turn-Off Delay Time | tD(OFF) | _ | 43 | _ | ns | $R_G = 6\Omega$, $I_D = -11.5A$ | |
| Turn-Off Fall Time | tF | _ | 33 | _ | ns | | |
| Reverse Recovery Time | trr | _ | 19 | _ | ns | 1 44.50 11/11 4000/1- | |
| Reverse Recovery Charge | Qrr | _ | 8.9 | _ | nC | Is = -11.5A, dl/dt = 100A/µs | |

Notes: 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.

- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.
- 7. Thermal resistance from junction to soldering point (on the exposed drain pad).
- 8. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.
- 9. Short duration pulse test used to minimize self-heating effect.
- 10. Guaranteed by design. Not subject to product testing.





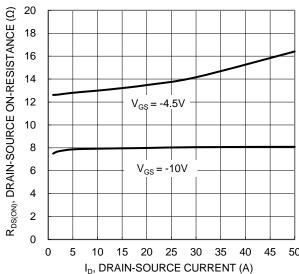
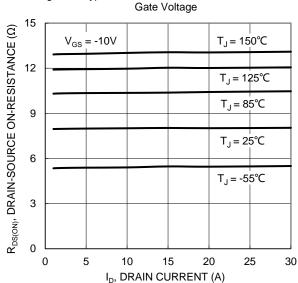
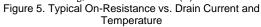


Figure 3. Typical On-Resistance vs. Drain Current and





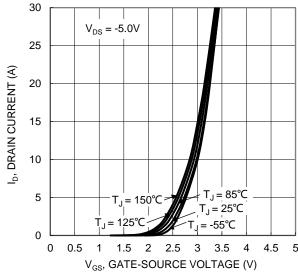
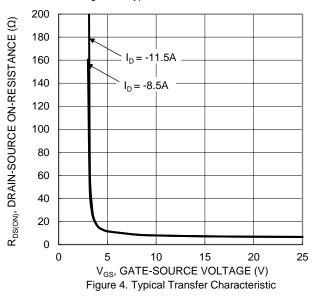


Figure 2. Typical Transfer Characteristic



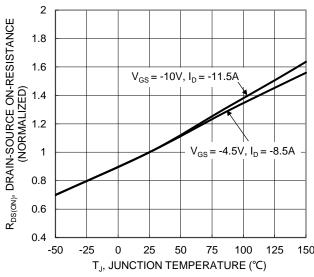


Figure 6. On-Resistance Variation with Temperature



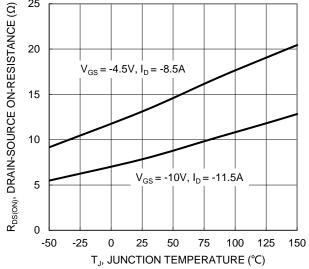
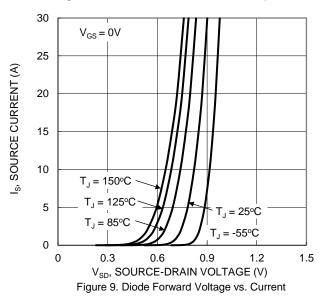


Figure 7. On-Resistance Variation with Temperature



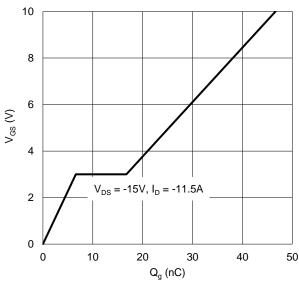


Figure 11. Gate Charge

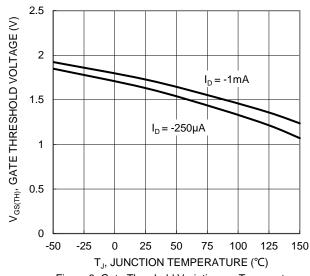
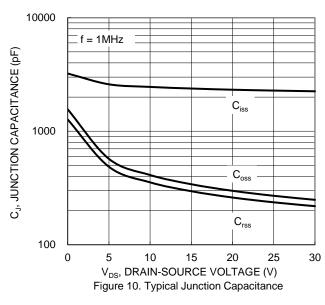
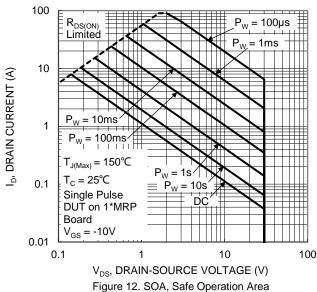


Figure 8. Gate Threshold Variation vs. Temperature







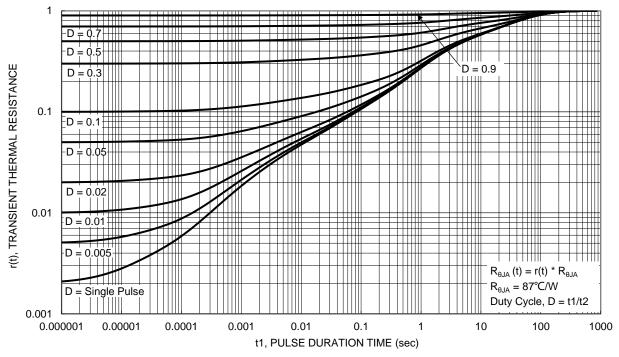


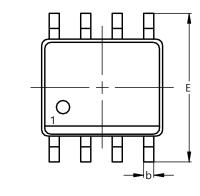
Figure 13. Transient Thermal Resistance

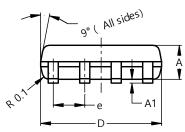


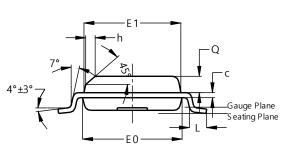
Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8





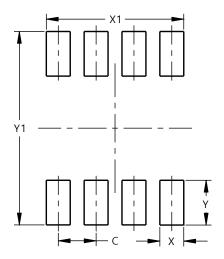


| SO-8 | | | | | |
|----------------------|------|------|------|--|--|
| Dim | Min | Max | Тур | | |
| Α | 1.40 | 1.50 | 1.45 | | |
| A1 | 0.10 | 0.20 | 0.15 | | |
| b | 0.30 | 0.50 | 0.40 | | |
| C | 0.15 | 0.25 | 0.20 | | |
| D | 4.85 | 4.95 | 4.90 | | |
| Е | 5.90 | 6.10 | 6.00 | | |
| E1 | 3.80 | 3.90 | 3.85 | | |
| E0 | 3.85 | 3.95 | 3.90 | | |
| е | | | 1.27 | | |
| h | - | | 0.35 | | |
| L | 0.62 | 0.82 | 0.72 | | |
| ø | 0.60 | 0.70 | 0.65 | | |
| All Dimensions in mm | | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8



| Dimensions | Value (in mm) | | | |
|-------------------|---------------|--|--|--|
| C | 1.27 | | | |
| Х | 0.802 | | | |
| X1 | 4.612 | | | |
| Y | 1.505 | | | |
| Y1 | 6.50 | | | |



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